

MANUFACTURING METHOD OF AN ELECTRONIC DEVICE PACKAGE

Abstract of the Disclosure

A method is for forming a plastic protective package for an electronic device integrated on a semiconductor and comprising an electronic circuit to be encapsulated in the protective package. The electronic device may be at least partially activated from outside of the protective package. The method may include providing a mold having a half-mold with an insert abutting towards the inside of the mold and an end having an element that can be elastically deformed to abut in pressing contact against at least one portion of the integrated circuit. The method may also include injecting a resin into the mold so that the protective package has a hole by the at least one portion of the electronic circuit.